

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	DB HITEK CO., LTD.	06/01/2021
RECEIVING PARTY DATA		
Name:	SAMSUNG ELECTRONICS CO., LTD.	
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU	
City:	SUWON-SI, GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	16677	
PROPERTY NUMBERS Total: 6		
Property Type	Number	
Patent Number:	8198659	
Patent Number:	7256133	
Patent Number:	7586142	
Patent Number:	8288830	
Patent Number:	7678677	
Patent Number:	8278754	
CORRESPONDENCE DATA		
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NAME OF SUBMITTER:	JOHN A. CASTELLANO	
SIGNATURE:	/John A. Castellano/	
DATE SIGNED:	06/07/2021	

Total Attachments: 3

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ASSIGNMENT**CORPORATE**

DE Hitek Co., Ltd., having a principal place of business at 432 Taeheran-ro, Daechi-dong, Gangnam-gu, Seoul, Republic of Korea (hereafter the "Assignor"), is the owner by respective Assignment of the United States Patent Applications identified in Attachment A (hereafter the "Patent Applications").

Samsung Electronics Co., Ltd., having a principal place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16677, Republic of Korea (hereafter the "Assignee"), desires to acquire all of the rights of the Patent Applications and all inventions described and claimed therein.

THEREFORE, in consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to it, Assignor hereby sells and assigns to the Assignee the entire right, title, and interest in and to the Patent Applications identified in Attachment A, and all inventions described and claimed therein, and in any and all reissues and reexaminations as well as any and all continuations and divisionals thereof, such entire right, title, and interest to be held and enjoyed by the above-named Assignee the same as they would have been held and enjoyed by the Assignor had this Assignment and sale not been made.

By its undersigned representative, the Assignor agrees

- a. to execute all papers necessary in connection with the Patent Applications and any reissues and reexaminations as well as any continuations and divisionals thereof and also to execute separate Assignment in connection with such applications or Letters Patent thereof as the Assignee may deem necessary or expedient;
- b. to execute all papers necessary in connection with any interference which may be declared concerning the Patent Applications and any reissues and reexaminations as well as any continuations and divisionals thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference; and
- c. to perform all affirmative acts which may be necessary to obtain a grant of a valid patent to the Assignee on inventions described in the Patent Applications and any reissues and reexaminations as well as any and all continuations and divisionals thereof.

The Assignor hereby covenants that it has the right to convey its interest in the Patent Applications identified in Attachment A, and that it has not executed, and will not execute, any agreement in conflict therewith.

The Assignor certifies that it is the Owner of the entire right, title, and interest in the Patent Applications identified in Attachment A by virtue of an Assignment for of the Patent Applications. This Assignment was recorded as shown in Attachment A.

The undersigned has reviewed the documents in the Patent Applications identified in Attachment A and, to the best of undersigned's knowledge and belief, title is in the Assignor identified above.

The undersigned is empowered to sign this certificate on behalf of the Assignor.

The undersigned hereby declares that all statements made herein of his/her own knowledge are true, and that all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements, and the like so made, are punishable by fine or imprisonment, or both, under Section 1001, Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing therefrom.

IN WITNESS WHEREOF, executed by the Assignor's undersigned representative on the date following the undersigned's name.

DB Hitek Co., Ltd.

By:

Seong jin Han



Title:

Vice president

Date:

June 1st, 2024

ATTACHMENT A

Application No.	Filing Date	Patent No.	Grant Date	Title
12/620,803	2009-11-18	8,198,659	2012-06-12	SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME
11/321,118	2005-12-28	7,256,133	2007-08-14	METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE
11/944,588	2007-11-23	7,586,142	2009-09-08	SEMICONDUCTOR DEVICE HAVING METAL-INSULATOR-METAL CAPACITOR AND METHOD OF FABRICATING THE SAME
12/648,230	2009-12-28	8,288,830	2012-10-16	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME
11/880,473	2007-07-20	7,678,677	2010-03-16	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF
12/582,849	2009-10-21	8,278,754	2012-10-02	METAL LINE IN SEMICONDUCTOR DEVICE AND METHOD FOR FORMING THE SAME